(12) PATENT APPLICATION PUBLICATION

(19) INDIA

(22) Date of filing of Application :21/11/2013

(21) Application No.9350/CHENP/2013 A

(43) Publication Date : 24/06/2016

(54) Title of the invention : INTEGRATED CIRCUIT DESIGN USING THROUGH SILICON VIAS

(51) International classification	:H01L25/07,H01L25/065,H01L23/522
(31) Priority Document No	:13/170020
(32) Priority Date	:27/06/2011
(33) Name of priority country	:U.S.A.
(86) International Application No Filing Date	:PCT/US2012/021416 :16/01/2012
(87) International Publication No	:WO 2013/002844
(61) Patent of Addition to Application Number Filing Date	:NA :NA
(62) Divisional to Application Number Filing Date	:NA :NA

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(57) Abstract :
In an integrated circuit (IC) structure the positioning of through silicon vias (TSVs) in terms of the physical layout of circuitry is described. An IC structure can include a plurality of first circuit elements (D1 G1 & S; 702 706 710 & 714; or 702 706 704 & 708); a plurality of second circuit elements (D2 G2 & S; 704 708 712 & 716; or 710 714 712 & 716); a plurality of first TSVs (410 & 510; 605 620; or 720 734); and a plurality of second TSVs (415 & 505; 625 640; or 736 750). The first and second circuit elements and the first and second TSVs together comprise a circuit block configuration. The circuit block configuration is symmetric with respect to at least one axis of symmetry. At least one of the first TSVs is a dummy TSV without which the circuit block configuration would not be symmetric.

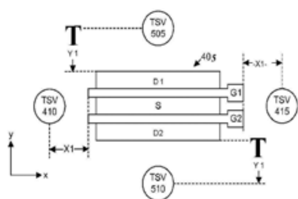

FIG. 5

No. of Pages : 40 No. of Claims : 14